## IV. REMARKS

Tanaka does not disclose any hole in the case (20). There is no hole formed on the case for communicating with the outside of the case to expose a part of the base member to the outside of the case wherein the base member has greater thermal conductivity than that of the case. Furthermore, although it teaches in column 3, lines 63-64, that the substrate (9) is a printed circuit board of a so-called high heat conduction type, Tanaka does not teach anything about the thermal conductivity of the mounting member or casing (20) (col. 5, line 44- col. 6, line 4). Thus, there is no evidence, nor can it be implied, that thermal conductivity of the substrate (9) is greater than that of the casing (20). In fact, the substrate (9) and the casing (20) are both made of aluminum.

Claims 13 and 18 now recite that the base member has a greater thermal conductivity than that of the cases. Since this is not expressed or implied in the disclosure of Tanaka, the rejection of claims 13-22 under 35 USC 103 should be withdrawn.

It is respectfully submitted that all of the claims present in the application are clearly novel and patentable, and are in proper form for allowance. Accordingly, favorable consideration and allowance is respectfully requested. Should any unresolved issues remain, the Examiner is invited to call Applicants' attorney at the telephone number indicated below.

The Commissioner is hereby authorized to charge payment for any fees associated with this communication or credit any over payment to Deposit Account No. 16-1350.

Respectfully submitted,

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## CERTIFICATE OF MAILING

Yarch 3,2004

I hereby certify that this correspondence is being deposited with the United States Postal Service on the date indicated below as first class mail in an envelope addressed to the Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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